

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	153	235/492.ccls. and ((wind winding roll\$5 wound\$4 reel\$6) with (electronic modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4)))	USPAT	OR	ON	2006/08/02 08:31
L2	32	"4897534".uref.	USPAT	OR	ON	2006/08/02 08:34
L3	27	"5055913".uref.	USPAT	OR	ON	2006/08/02 08:36
L4	9	"5670001".uref.	USPAT	OR	ON	2006/08/02 08:37
L8	55	"438"/\$.ccls. and ((liquid\$4 wet melt\$4 molten soft\$8) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4 hard\$4)) and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4))	USPAT	OR	ON	2006/08/02 10:11
L9	1	("6924211" "6753614").uref.	USPAT	OR	ON	2006/08/02 08:58
L10	48	"438"/\$.ccls. and ((liquid\$4 wet melt\$4 molten soft\$8) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4 hard\$4)) and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4))	US-PGPUB	OR	ON	2006/08/02 08:56
L11	2	("6924211" "6753614").pn.	USPAT	OR	ON	2006/08/02 09:36
L12	1	"5030308".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:58
L13	1	"5667073".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:58
L14	1	"6103554".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:58
L15	1	"6412641".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:59
L16	8	("5874142" "7056767" "6097602" "5670001" "4897534" "5055913" "6924211" "6753614").pn.	USPAT	OR	ON	2006/08/02 09:39

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L17	157	"257"/\$.ccls. and ((liquid\$4 wet melt\$4 molten soft\$8) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4 hard\$4)) and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4))	USPAT	OR	ON	2006/08/02 10:12
S1	59	235/492.ccls. and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6))	USPAT	OR	ON	2006/07/31 13:56
S2	201	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6)) and (cut\$6 with module)	USPAT	OR	ON	2006/07/31 13:57
S3	149	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 laminat\$6) with (modul\$4 chip semiconduc\$6)) and (cut\$6 with (module semiconduc\$6))	USPAT	OR	ON	2006/07/31 14:24
S9	182	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 laminat\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet dry\$6 dried melt\$4) with (glue adhes\$6 laminat\$6 paste\$4 bond\$4))	USPAT	OR	ON	2006/08/01 10:02
S10	101	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 laminat\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet dry\$6 dried melt\$4) with (glue adhes\$6 laminat\$6 paste\$4 bond\$4)) and tape	USPAT	OR	ON	2006/08/01 10:06

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S13	23	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:12
S14	25	((wind winding roll\$5 wound\$4 reel\$6) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:22
S15	42	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:38
S16	53	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	US-PGPUB	OR	ON	2006/08/01 10:40

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S17	2	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:41
S18	44	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with (module chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:56
S19	1	"4897534".pn.	USPAT	OR	ON	2006/08/01 10:51
S20	17	((wind winding roll\$5 wound\$4 reel\$6) with (electronic)) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with electronic) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:54
S21	176	((wind winding roll\$5 wound\$4 reel\$6) with (electronic modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/02 08:40
S22	5	"5874142".uref.	USPAT	OR	ON	2006/08/01 11:17

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S23	153	((wind winding roll\$5 wound\$4 reel\$6) with (electronic modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	US-PGPUB	OR	ON	2006/08/02 08:14
S24	1405	((wind winding roll\$5 wound\$4 reel\$6) with (tape web)) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:24
S25	217	((wind winding roll\$5 wound\$4 reel\$6) with (tape web) with (liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:27
S27	46	((wind winding roll\$5 wound\$4 reel\$6) with (tape web) with (liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4) with (heat\$6 hot\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:32
S28	48	((wind winding roll\$5 wound\$4 reel\$6) with (tape web) with (liquid\$4 wet melt\$4 molten soft\$6) with (glue adhes\$6 paste\$4 bond\$4) with (heat\$6 hot\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:38